(12) International Application Status Report

Received at International Bureau: 16 October 2019 (16.10.2019)
Information valid as of: 06 May 2020 (06.05.2020)
Report generated on: 22 September 2020 (22.09.2020)

(10) Publication number:
WO2020/105289

(43) Publication date:
28 May 2020 (28.05.2020)

(26) Publication language:
Japanese (JA)

(21) Application Number:
PCT/JP2019/038866

(22) Filing Date:
02 October 2019 (02.10.2019)

(25) Filing language:
Japanese (JA)

(31) Priority number(s):
2018-216720 (JP)

(31) Priority date(s):
19 November 2018 (19.11.2018)

(31) Priority status:
Priority document received (in compliance with PCT Rule 17.1)

(51) International Patent Classification:
C25D 5/16 (2006.01); **C25D 1/04** (2006.01); **C25D 5/10** (2006.01); **C25D 7/00** (2006.01); **C25D 7/06** (2006.01); **H05K 3/18** (2006.01); **H05K 3/38** (2006.01)

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(54) Title (EN): SURFACE-TREATED COPPER FOIL, CARRIER-ATTACHED COPPER FOIL, COPPER-CLAD LAMINATE, AND PRINTED WIRING BOARD

(54) Title (FR): FEUILLE DE CUIVRE TRAITÉE EN SURFACE, FEUILLE DE CUIVRE FIXÉE À UN SUPPORT, STRATIFIÉ PLAQUÉ DE CUIVRE ET CARTE DE CIRCUITS IMPRIMÉS

(54) Title (JA): 表面処理銅箔、キャリア付銅箔、銅張積層板及びプリント配線板

(57) Abstract:

(EN): Provided is a surface-treated copper foil that, in the case of use in the SAP method, can provide a resin substrate with a surface profile that can effectively prevent the generation of deposition that can be produced in a circuit in the step of etching an electroless copper plating layer. The surface-treated copper foil is a surface-treated copper foil that has a treated surface on at least one side thereof. When a resin film is hot-press bonded to the treated surface, the surface shape of the treated surface is transferred to the surface of the resin film, and the surface-treated copper film is then removed by etching, the skewness Ssk for the surface of the remaining resin film, as measured in accordance with ISO 25178, is less than or equal to -0.6.

(FR): L'invention concerne une feuille de cuivre traitée en surface qui, dans le cas d'une utilisation dans le procédé SAP, peut fournir un substrat de résine ayant un profil de surface qui peut empêcher efficacement la production d'un dépôt qui peut être produit dans un circuit à l'étape de gravure d'une couche de placage de cuivre autocatalytique. La feuille de cuivre traitée en surface a une surface traitée sur au moins un côté de celle-ci. Lorsqu'un film de résine est lié par pressage à chaud à la surface traitée, le profil de surface de la surface traitée est transféré à la surface du film de résine et la feuille de cuivre traitée en surface est retirée par gravure, l'asymétrie Ssk de la surface du film de résine restant, mesurée conformément à la norme ISO 25178, étant inférieure ou égale à -0,6.

(JA): ＳＡＰ法に用いた場合に、無電解銅めっき層のエッチング工程において、回路に生じうる差し込みの発生を効果的に抑制できる表面プロファイルを樹脂基材に付与可能な、表面処理銅箔が提供される。この表面処理銅箔は、少なくとも一方の側に処理表面を有する表面処理銅箔であって、処理表面に樹脂フィルムを熱圧着して処理表面の表面形状を樹脂フィルムの表面に転写し、エッチングにより表面処理銅箔を除去した場合に、残された樹脂フィルムの表面における、ＩＳＯ２５１７８に準拠して測定されるスキューネスＳｓｋが-０.６以下となる。

International search report:

Received at International Bureau: 23 December 2019 (23.12.2019) [JP]

International Report on Patentability (IPRP) Chapter II of the PCT:

Not available

(81) Designated States:

AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IR, IS, JO, JP, KE, KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW

European Patent Office (EPO) : AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR

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Eurasian Patent Organization (EAPO) : AM, AZ, BY, KG, KZ, RU, TJ, TM